

ABSTRACT OF THE INVENTION

A heat-dissipating fin of a heat sink for improving thermal conduction is disclosed. The heat sink has a base plate and a plurality of heat-dissipating fins. The base plate includes a first surface contacting with a heat source, and a second surface having a plurality of grooves orderly formed on the second surface. The heat-dissipating fin of the heat sink has the feature that the thickness of the heat-dissipating fin is not uniform, and the thickness of a bottom surface of the heat-dissipating fin facing the groove is greater than the other portions of the heat-dissipating fin.